

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Currently Amended) A single-sided paper phenolic resin copper-clad laminate comprising a phenolic resin impregnated paper base having:

copper foils adapted to have terminals of electronic components soldered thereon, the copper foils being directly laminated to said phenolic resin impregnated paper base on a face side of said paper base, and

resists applied on the face side, except an area adapted to have the terminals of electronic components soldered on the copper foils,

wherein resists formed of a same material as the resists on the face side are applied on a reverse side of the phenolic resin impregnated paper base, and

wherein a position and configuration of the resists applied on the reverse side of the phenolic resin impregnated paper base match with those of the resists applied on the face side of the phenolic resin impregnated paper base.

2. (Canceled)

3. (Previously Presented) A single-sided paper phenolic resin copper-clad laminate as claimed in claim 1, wherein said resist is formed of a synthetic resin.

4. (Canceled)

5. (Previously Presented) A single-sided paper phenolic resin copper-clad laminate as claimed in claim 3, wherein the synthetic resin is an epoxy resin.

6. (Canceled)

7. (Previously Presented) A single-sided paper phenolic resin copper-clad laminate as claimed in claim 1, wherein the terminals of electric components are soldered with lead-free solder.

8. (Canceled)

9. (Canceled)

10. (Currently Amended) A single-sided paper phenolic resin copper-clad

laminate as claimed in claim 1, comprising a phenolic resin impregnated paper base having:

_____ copper foils adapted to have terminals of electronic components soldered

thereon, the copper foils being directly laminated to said phenolic resin impregnated paper

base on a face side of said paper base, and

_____ resists applied on the face side, except an area adapted to have the terminals of
electronic components soldered on the copper foils,

_____ wherein resists formed of a same material as the resists on the face side are
applied on a reverse side of the phenolic resin impregnated paper base, and

_____ wherein the resists applied on the reverse side of the phenolic resin

impregnated paper base are applied with a checkered pattern.

11. (New) A single-sided paper phenolic resin copper-clad laminate as claimed in claim 10, wherein said resist is formed of a synthetic resin.

12. (New) A single-sided paper phenolic resin copper-clad laminate as claimed in claim 11, wherein the synthetic resin is an epoxy resin.

13. (New) A single-sided paper phenolic resin copper-clad laminate as claimed in claim 10, wherein the terminals of electric components are soldered with lead-free solder.